506140464 07/07/2020

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
CHUN-CHIEH CHAN	07/03/2020
WEI-LUN HUANG	07/03/2020
CHIA-LUNG HUNG	07/03/2020
YUNG-MING LIN	07/03/2020

RECEIVING PARTY DATA

Name:	REALTEK SEMICONDUCTOR CORP.
Street Address:	NO.2, INNOVATION ROAD II, HSINCHU SCIENCE PARK,
City:	HSINCHU
State/Country:	TAIWAN
Postal Code:	300

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	16921996

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER:	108P001042US
NAME OF SUBMITTER:	ZHUO XU
SIGNATURE:	/ZHUO XU/
DATE SIGNED:	07/07/2020

Total Attachments: 3

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> **PATENT** REEL: 053133 FRAME: 0629 506140464

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PATENT REEL: 053133 FRAME: 0630

ASSIGNMENT DEED

Attorney docket No. 108P001042US

This Assignment agreement is applicable to an invention entitled (invention Title):

IMAGE PROCESSING CHIP

	The PATENT RIGHTS referred to in this agreement are:
(Check o	n o)
	a Patent Application for this invention, executed by the ASSIGNOR(S) concurrently with this Assignment
	□ U.S. Patent Application Serial No.
	The PATENT RIGHTS assigned under this agreement are:
(Check O	ne)
	■ U.S. Patent rights only
of any U.S	worldwide Patent rights. In this case, the assignee shall have the right to claim the benefit of the filing date S. Patent Application identified above.
	I/WE believe that I/WE am/are the original inventor(s) of a claimed invention in the application.
	The above-identified Application was made or authorized by me/us.
1001 by fi	I/WE hereby acknowledge that any will false statements made in this Assignment is punishable under 18 USC ne or imprisonment of not more than five (5) years, or both.
	The ASSIGNOR(S) referred to in this agreement is (or are):
	(Full name of sole or first assignor) CHUN-CHIEH CHAN (FAMILY NAME: CHAN)
(Address)	NO.2, INNOVATION ROAD II, HSINCHU SCIENCE PARK, HSINCHU 300, TAIWAN, R.O.C.
	(Full name of second joint assignor) WEI-LUN HUANG (FAMILY NAME: HUANG)
(Address)	NO. 3, LN. 55, LIDE 11TH RD., EAST DIST., TAINAN CITY 701, TAIWAN, R.O.C.
	(Full name of third joint assignor) CHIA-LUNG HUNG (FAMILY NAME: HUNG)
(Address)	2F., NO. 4, LN. 196, ZILI ST., XINZHUANG DIST., NEW TAIPEI CITY 242, TAIWAN, R.O.C.
	(Full name of fourth joint assignor) YUNG-MING LIN (FAMILY NAME: LIN)
(Address)	NO. 238-1, SEC. 3, DONGGUAN RD., HEPING DIST., TAICHUNG CITY 424, TAIWAN, R.O.C.
	18.00
	(Full name of fifth joint assignor, if any)
(Address)	
	☐ Additional assignors are being named on separately numbered sheets attached hereto.
	The sole or first ASSIGNEE(S) referred to in this agreement is (or are):
(Name of	f Assignee) REALTEK SEMICONDUCTOR CORP.

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The sole or first ASSIGNE	E is: (Check One)		
	☐an individual		
	a partnership		
	■a Corporation of T	AIWAN, R.O.C. (State or	Country)
The second AS	SIGNEE(S) (if any) referred to in the		,,
		• , ,	
(Address of Assignee)			
			
The second ASSIGNEE is	: (Check One)		
	□an individual		
	☐ a partnership		
	a Corporation of	····	(State or Country)
☐ Additio	nal assignees are being named on	separately numbered sheets atta	ched hereto.
	t(S), in consideration of \$1.00 paid hich is acknowledged, have and do		
the full and exclu	usive right to the invention;		
an equal interes all continuation, continuation the PATENT RIGHTS; and	t in and to the entire right, title, and on-in-part, divisional, re-issue, and i	interest in and to the PATENT Ri re-examination patents and pater	GHTS in the invention, and applications relating to
the right to claim	priority under 35 U.S.C. § 119, ba	sed on any earlier foreign applica	tions for this invention.
request(s) the Director of F	tent Applications assigned under to Patents and Trademarks to issue a entire right, title, and interest, for th	I Letters Patent to the ASSIGNEE	(S) as the ASSIGNEE(S)
known to the ASSIGNOR(all divisional, continuation, papers to cause any and a	SIGNOR(S) agree(s) to communica S) respecting said invention, and to substitute, renewal, reexamination II Letters Patent to be issued to sa esirable to aid said ASSIGNEE(S), n.	stify in any legal proceedings, sig , and reissue applications, execut d ASSIGNEE(S), make all rightfu	n all lawful papers, execute e all necessary assignmen oaths, and generally do
IAN/E hereby give our Attor	ney authorization to insert the Seri	al Number and filing data of the a	nove referenced Patent
Application when known.			oove-relevenced ratent
culled as	CHUN-CHIEH CHAN (F	AMILY NAME: CHAN)	
CPIPO. CA	10N-OPTOP	2	020.7.3
(Signature of Si	ole or first assignor)		(Date)
	WEI-LUN HUANG (FAN	IILY NAME: HUANG)	
477-1116	1 MILANG	2	020.7.3
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CHIA-LUNG HUNG (FAMILY NAME: HUNG)

CHIA-LUNG HUNG	2020.7.3
(Signature of third assignor)	(Date)
YUNG-MING LIN (FAMILY NAME: LI	N)
TUNG MING LIN	2020.7.3
(Signature of fourth assignor)	(Date)
(Signature of fifth assignor, if any)	(Date)

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PATENT REEL: 053133 FRAME: 0633

RECORDED: 07/07/2020